



MJ N-Channel Super Trench II Power MOSFET

Description

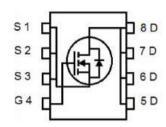
The MJXP065N10GU uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

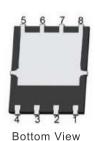
- ♦ V_{DS}=100V,I_D=90A R_{DS(ON)}=5.9mΩ (typical) @ V_{GS}=10V
- ◆ Excellent gate charge x R_{DS(on)} product(FOM)
- ♦ Very low on-resistance R_{DS(on)}
- ◆ 150°C operating temperature
- ◆ Pb-free lead plating

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification







Schematic Diagram

DFN 5X6

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P065N10GU	MJXP065N10GU	DFN5X6-8L	2	-	9

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ΙD	90	А
Drain Current-Continuous(Tc =100℃)	ID(100°C)	65	А
Pulsed Drain Current	Ідм	360	А
Maximum Power Dissipation	Po	110	W
Derating factor		0.88	W/°C
Single pulse avalanche energy (Note 5)	Eas	380	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	1.14	°C/W
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Electrical Characteristics (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVpss	V _{GS} =0V I _D =250µA	100	-	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	2	3	4	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V,I _D =45A	-	5.9	6.5	mΩ
Forward Transconductance	grs	V _{DS} =5V,I _D =45A	-	60	-	S
Dynamic Characteristics (Note 4)		I	1	1		1
Input Capacitance	Clss		-	3600	-	PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	335	_	PF
Reverse Transfer Capacitance	Crss	•	-	19.5	_	PF
Switching Characteristics (Note 4)	-					
Turn-on Delay Time	t _{d(on)}		-	17	-	nS
Turn-on Rise Time	tr	VDD=50V,ID=45A	-	11	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =3Ω	-	36	-	nS
Turn-Off Fall Time	tr		-	9	_	nS
Total Gate Charge	Qg		-	60	-	nC
Gate-Source Charge	Qgs	V _{DS} =50V,I _D =45A V _{GS} =10V	-	20	-	nC
Gate-Drain Charge	Qgd		-	15	-	nC
Drain-Source Diode Characteristics		I		<u> </u>		1
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =45A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	90	А
Reverse Recovery Time	trr	TJ=25°C,IF=45A	-	62	_	nS
Reverse Recovery Charge	Qrr	di/dt= 100A/µs (Note 3)	_	109		nC

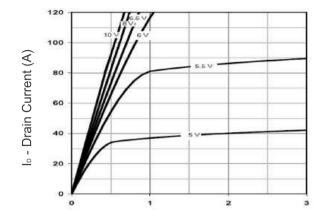
Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production



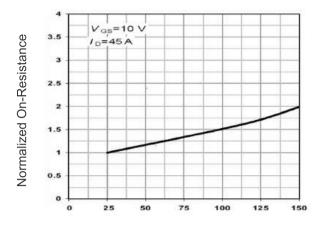


Typical Electrical and Thermal Characteristics

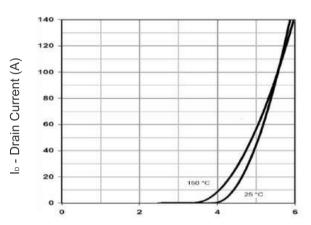


Vds Drain-Source Voltage (V)

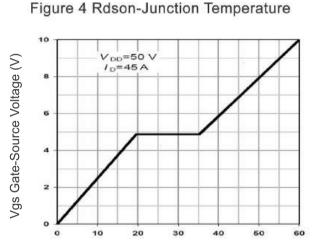
Figure 1 Output Characteristics



T_J-Junction Temperature (°C)



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics



Qg Gate Charge (nC)
Figure 5 Gate Charge

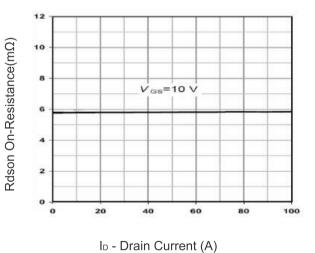
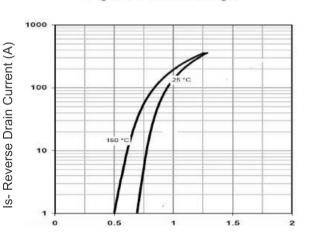


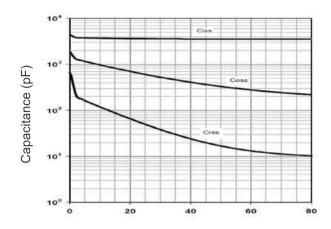
Figure 3 Rdson- Drain Current



Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward



lo - Drain Current (A)



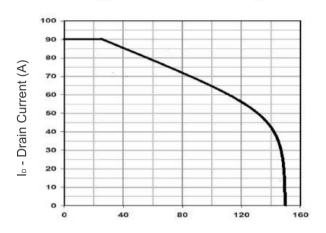
140 120 (M) 100 100 80 60 40 20 0 40 80 120 160

Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

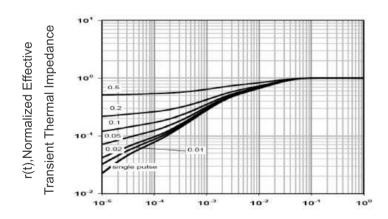
10³
10²
10¹
10⁰
10¹
10¹
10⁰
10¹
10²
10²
10²
10²
10³
10²
10³

T_J-Junction Temperature(°C) Figure 9 Power De-rating



Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area

T_J-Junction Temperature(°C) Figure 10 Current De-rating



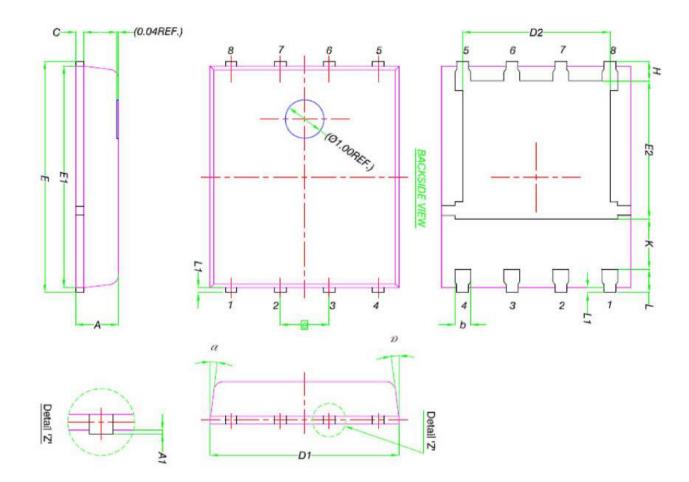
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

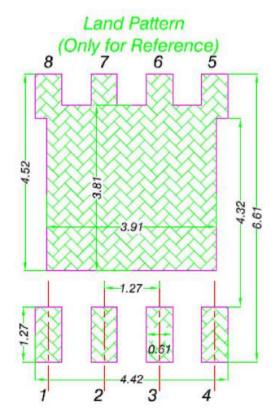




DFN5X6-8L Package Information



DIM.	MILLIMETERS			
	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0		0.05	
b	0.33	0.41	0.51	
С	0.20	0.25	0.30	
D1	4.80	4.90	5.00	
D2	3.61	3.81	3.96	
Ε	5.90	6.00	6.10	
E1	5.70	5.75	5.80	
E2	3.38	3.58	3.78	
е	1.27 BSC			
Н	0.41	0.51	0.61	
K	1.10		*	
L	0.51	0.61	0.71	
L1	0.06	0.13	0.20	
α	O°		12°	





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